

RELIABILITY DATA

LT1122 / LT1169

8/21/2006

• OPERATING LIFE TEST

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS ⁽¹⁾ AT +125°C	NUMBER OF FAILURES ⁽²⁾
HERMETIC	208	9003	9401	672.09	0
PLASTIC DIP	3,582	9140	0537	6,867.69	0
SOIC/SOT/MSOP	1,843	9805	0525	694.33	0
	5,633			8,234.11	0

• HIGHLY ACCELERATED STRESS TEST AT +131°C/85%RH

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS ⁽⁴⁾ AT +85°C	NUMBER OF FAILURES
PLASTIC DIP	644	9140	0042	1,177.88	0
SOIC/SOT/MSOP	493	9122	0516	504.24	0
	1,137			1,682.12	0

• PRESSURE COOKER TEST AT 15 PSIG, +121°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES
PLASTIC DIP	3,026	9146	0537	140.53	0
SOIC/SOT/MSOP	2,115	9122	0613	65.58	0
	5,141			206.11	0

• TEMP CYCLE FROM -65°C to +150°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
PLASTIC DIP	755	9140	0311	75.58	0
SOIC/SOT/MSOP	240	9122	0044	24.00	0
	995			99.58	0

• THERMAL SHOCK FROM -65°C to +150°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
PLASTIC DIP	230	9146	9627	23.00	0
SOIC/SOT/MSOP	190	9122	0044	19.00	0
	420			42.00	0

(1) Assumes Activation Energy = 1.0 Electron Volts

(2) Failure Rate Equivalent to +55°C, 60% Confidence Level = 0.22 FITS

(3) Mean Time Between Failures in Years = 518,532

(4) Assumes 20X Acceleration from 85°C to +131°C

Note: 1 FIT = 1 Failure in One Billion Hours.